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**APPLICATION DATA SHEET
UNDER 37 CFR §1.76**

(1) Inventor Information

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(2) Assignee Information

Name Line One:: Toppoly Optoelectronics Corp.
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Country:: Taiwan, R.O.C.
Postal or ZIP Code:: 350

(3) Correspondence Information

Customer No.: 3624
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(4) Application Information

Title Line One:: PROCESS FOR FORMING POLYCRYSTALLINE
Title Line Two:: SILICON LAYER BY LASER CRYSTALLIZATION
Total Drawing Sheets:: 10
Drawing Type:: Formal
Application Type:: Utility
Docket No.: TET-PT049

(5) Representative Information

Representative Customer No.: 3624

(6) Foreign Priority Information

Foreign Application One::	092118424
Filing Date::	July 4, 2003
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Priority Claimed::	YES